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(54) **Method of cutting out chips for a plurality of sensor elements from laminated body**

Verfahren zum Schneiden von Chips aus einer Vielzahl von Sensorelementen eines laminierten Körpers

Procédé de découpage de puces pour une pluralité d'éléments capteurs dans un corps stratifié

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(56) References cited:
EP-A1- 1 626 273 **EP-A2- 0 309 360**
JP-A- 8 271 476 **US-A- 6 027 622**
US-A1- 2005 252 770 **US-A1- 2007 007 136**
US-B1- 6 620 302

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